

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE <div style="border: 1px solid black; border-radius: 50%; width: 100px; height: 100px; display: flex; align-items: center; justify-content: center; margin: 0 auto;"> <div style="text-align: center;">             AUG 10 2000              PATENT &amp; TRADEMARK OFFICE           </div> </div>		ATTY. DOCKET NO.	SERIAL NO. <b>09/146,723</b>
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)			APPLICANT <b>Fornworth et al</b>		
			FILING DATE <b>9/3/98</b>	GROUP <b>3729</b>	

  

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<div style="font-size: 2em;">↓</div>	AA	6,063,701	05/16/00	Kuwazaki et al.	—	—
	AB	5,899,737	05/04/99	Trabucco	—	—
	AC	5,763,854	06/09/98	Dittman et al.	—	—
	AD	5,762,258	06/09/98	Le Coz et al.	—	—
	AE	5,495,089	02/27/96	Freedman et al.	—	—
	AF	5,431,332	07/11/95	Kirby et al.	—	—
	AG					
	AH					
	AI					
	AJ					
AK						

  

FOREIGN PATENT DOCUMENTS							
Document Number	Date	Country	Class	Subclass	Translation		
					Yes	No	
AL	WO 99/17593	04/08/99	PCT	—	—		
AM	8-118005 A	05/14/96	Japan	—	—		
AN							
AO							
AP							

  

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)		
<div style="font-size: 2em;">↓</div>	AR	Kasulke et al., <i>Solder Ball Bumper (SBB) - A Flexible Equipment for FC, CSP, BGA and Printed Circuit Boards/An Innovative Solution for,</i> <i>Solder Application Solder Ball Bumper (SBB),</i> Pac Tech Packaging Technologies GmbH and Fraunhofer IZM, pp. 1-8.
	AS	
	AT	

  

EXAMINER <b>A. Deth Tugberg</b>	DATE CONSIDERED <b>9/10/00</b>
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
M122-981SERIAL NO.  
09/148,723LIST OF ART CITED BY APPLICANT  
(Use several sheets if necessary)APPLICANT  
Farnworth et al.FILING DATE  
09/03/98GROUP  
3729

U.S. PATENT DOCUMENTS

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	AA						
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## OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

AR		Kasulke, P., et al., "Solder Ball Bumper (SBB) - A Flexible Equipment for FC, CSP, BGA and Printed Circuit Boards", "An Innovative Solution for Solder Application Solder Ball Bumper (SBB)", Pac Tech Packaging Technologies GmbH and
		Fraunhofer IZM, pp. 1-8.
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